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## SN74ALVC164245-EP 16-BIT 2.5-V TO 3.3-V/3.3-V TO 5-V LEVEL-SHIFTING TRANSCEIVER WITH 3-STATE OUTPUTS

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#### **FEATURES DGG OR DL PACKAGE Controlled Baseline** (TOP VIEW) - One Assembly/Test Site, One Fabrication 48 10E 1DIR [ 1B1 **∏** 2 47∏ 1A1 **Enhanced Diminishing Manufacturing** 1B2**∏**3 46 ¶ 1A2 Sources (DMS) Support GND ∏ 4 45 GND **Enhanced Product-Change Notification** 1B3 **∏** 5 44 1 1A3 Qualification Pedigree(1) 43 1A4 1B4 ∏ Member of the Texas Instruments Widebus™ (3.3 V, 5 V) V<sub>CCB</sub> 7 42 V<sub>CCA</sub> (2.5 V, 3.3 V) **Family** 1B5 **∏** 8 41**□** 1A5 Max t<sub>pd</sub> of 5.8 ns at 3.3 V 1B6 **∏** 9 40**∏** 1A6 GND [] 10 39 GND ±24-mA Output Drive at 3.3 V 1B7 [ 11 38**∏** 1A7 Control Inputs VIH/VIL Levels Are Referenced 1B8 **∏** 12 37 T 1A8 to V<sub>CCA</sub> Voltage 2B1 **1** 13 36 2A1 Latch-Up Performance Exceeds 250 mA Per 2B2 [ 35 2A2 14 JESD 17 GND **1**5 34 GND (1) Component qualification in accordance with JEDEC and 2B3 **1** 16 33 7 2A3 industry standards to ensure reliable operation over an 32 1 2A4 2B4 **∏** 17 extended temperature range. This includes, but is not limited 31 V<sub>CCA</sub> (2.5 V, 3.3 V) to, Highly Accelerated Stress Test (HAST) or biased 85/85, (3.3 V, 5 V) V<sub>CCB</sub> 18 temperature cycle, autoclave or unbiased HAST, 2B5 **1** 19 30 2A5 electromigration, bond intermetallic life, and mold compound 2B6 **1**20 29 2A6 life. Such qualification testing should not be viewed as justifying use of this component beyond specified GND Π 21 28**∏** GND performance and environmental limits. 2B7 **∏** 22 27 1 2A7 2B8 **1** 23 26 2A8 2DIR [ 25 20E

### **DESCRIPTION/ORDERING INFORMATION**

This 16-bit (dual-octal) noninverting bus transceiver contains two separate supply rails. B port has  $V_{CCB}$ , which is set to operate at 3.3 V and 5 V. A port has  $V_{CCA}$ , which is set to operate at 2.5 V and 3.3 V. This allows for translation from a 2.5-V to a 3.3-V environment, and vice versa, or from a 3.3-V to a 5-V environment, and vice versa.

The SN74ALVC164245 is designed for asynchronous communication between data buses. The control circuitry (1DIR, 2DIR,  $\overline{10E}$ , and  $\overline{20E}$ ) is powered by  $V_{CCA}$ .

To ensure the high-impedance state during power up or power down, the output-enable  $(\overline{OE})$  input should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

### ORDERING INFORMATION

T <sub>A</sub>	PACKAGE <sup>(1)</sup>		ORDERABLE PART NUMBER	TOP-SIDE MARKING	
	SSOP - DL	Reel of 1000	CALVC164245IDLREP	ALVC164245	
–40°C to 85°C	TSSOP - DGG	Reel of 2000	CALVC164245IDGGREP	ALVC164245	
-40°C 10 85°C	VFBGA – GQL	Reel of 1000	CALVC164245IGQLREP	VC4245EP	
	VFBGA – ZQL (Pb-free)	Reel of 1000	CALVC164245IZQLREP	VC4245EP	
–55°C to 125°C	SSOP – DGG Reel of 2000		CALVC164245MDGGREP	C164245MEP	

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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Widebus is a trademark of Texas Instruments.





## GQL OR ZQL PACKAGE (TOP VIEW)

	_	1	2	3	4	5	6
Α		$\circ$	$\bigcirc$	$\bigcirc$	$\bigcirc$	$\bigcirc$	$\circ$
В		$\bigcirc$	$\bigcirc$	$\bigcirc$	$\bigcirc$	$\bigcirc$	$\bigcirc$
С		$\bigcirc$	$\bigcirc$	$\bigcirc$	$\bigcirc$	$\bigcirc$	$\bigcirc$
D		$\bigcirc$	$\bigcirc$	$\bigcirc$	$\bigcirc$	$\bigcirc$	$\bigcirc$
Е		$\bigcirc$	$\bigcirc$			$\bigcirc$	$\bigcirc$
F		$\bigcirc$	$\bigcirc$			$\bigcirc$	$\bigcirc$
G		$\bigcirc$	$\bigcirc$	$\bigcirc$	$\bigcirc$	$\bigcirc$	$\bigcirc$
н		$\bigcirc$	$\bigcirc$	$\bigcirc$	$\bigcirc$	$\bigcirc$	$\bigcirc$
J		$\bigcirc$	$\bigcirc$	$\bigcirc$	$\bigcirc$	$\bigcirc$	$\bigcirc$
ĸ		$\bigcirc$	$\bigcirc$	$\bigcirc$	$\bigcirc$	$\bigcirc$	$\bigcirc$
	•						

## TERMINAL ASSIGNMENTS(1)

	1	2	3	4	5	6
Α	1DIR	NC	NC	NC	NC	1 <del>OE</del>
В	1B2	1B1	GND	GND	1A1	1A2
С	1B4	1B3	V <sub>CCB</sub>	$V_{CCA}$	1A3	1A4
D	1B6	1B5	GND	GND	1A5	1A6
E	1B8	1B7			1A7	1A8
F	2B1	2B2			2A2	2A1
G	2B3	2B4	GND	GND	2A4	2A3
Н	2B5	2B6	V <sub>CCB</sub>	$V_{CCA}$	2A6	2A5
J	2B7	2B8	GND	GND	2A8	2A7
K	2DIR	NC	NC	NC	NC	2 <del>0E</del>

(1) NC - No internal connection

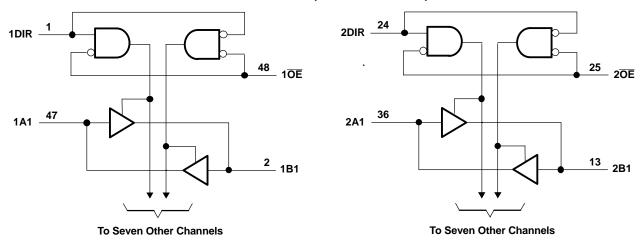
## FUNCTION TABLE (EACH 8-BIT SECTION)

INP	UTS	OPERATION
ŌĒ	DIR	OPERATION
L	L	B data to A bus
L	Н	A data to B bus
Н	X	Isolation

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### **LOGIC DIAGRAM (POSITIVE LOGIC)**



Pin numbers shown are for the DGG and DL packages.

## Absolute Maximum Ratings<sup>(1)</sup>

over operating free-air temperature range for  $V_{CCB}$  at 5 V and  $V_{CCA}$  at 3.3 V (unless otherwise noted)

			MIN	MAX	UNIT
$V_{CCA}$	Supply voltage range		-0.5	4.6	<b>V</b>
$V_{CCB}$	Supply voltage range		-0.5	6	V
		Except I/O ports <sup>(2)</sup>	-0.5	6	
$V_{I}$	Input voltage range	I/O port A <sup>(3)</sup>	-0.5	V <sub>CCA</sub> + 0.5	V
		I/O port B <sup>(2)</sup>	-0.5	V <sub>CCB</sub> + 0.5	
I <sub>IK</sub>	Input clamp current	V <sub>I</sub> < 0		-50	mA
I <sub>OK</sub>	Output clamp current	put clamp current $V_O < 0$		-50	mA
Io	Continuous output current			±50	mA
	Continuous current through each V <sub>CC</sub> or GND			±100	mA
		DGG package		70	
$\theta_{JA}$	Package thermal impedance (4)	DL package		63	
		GQL/ZQL package		42	
T <sub>stg</sub>	Storage temperature range		-65	150	°C

<sup>(1)</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

This value is limited to 6 V maximum.

This value is limited to 4.6 V maximum.

The package thermal impedance is calculated in accordance with JESD 51-7.



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## **Recommended Operating Conditions**(1)

for  $V_{CCB}$  at 3.3 V and 5 V

			MIN	MAX	UNIT
$V_{CCB}$	/ <sub>CCB</sub> Supply voltage			5.5	V
$V_{IH}$	High-level input voltage		2		V
W	Low lovel input valtage	V <sub>CCB</sub> = 3 V to 3.6 V		0.7	V
$V_{IL}$	Low-level input voltage	V <sub>CCB</sub> = 4.5 V to 5.5 V		0.8	V
V <sub>IB</sub>	Input voltage				V
$V_{OB}$	Output voltage				V
I <sub>OH</sub>	High-level output current			-24	mA
I <sub>OL</sub>	Low-level output current			24	mA
$\Delta t/\Delta v$	∆t/∆v Input transition rise or fall rate			10	ns/V
т	Operating free air temperature	CALVC16245I	-40	85	°C
T <sub>A</sub>	Operating free-air temperature CALVC16245M		-55	125	C

<sup>(1)</sup> All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

## Recommended Operating Conditions<sup>(1)</sup>

for  $V_{\text{CCA}}$  at 2.5 V and 3.3 V

			MIN	MAX	UNIT
$V_{CCA}$	Supply voltage		2.3	3.6	V
V	High level input valtage	$V_{CCA} = 2.3 \text{ V to } 2.7 \text{ V}$	1.7		V
V <sub>IH</sub>	High-level input voltage	V <sub>CCA</sub> = 3 V to 3.6 V	2		V
V	Low lovel input voltage	V <sub>CCA</sub> = 2.3 V to 2.7 V		0.7	V
$V_{IL}$	Low-level input voltage	V <sub>CCA</sub> = 3 V to 3.6 V		0.8	V
V <sub>IA</sub>	Input voltage				V
V <sub>OA</sub>	Output voltage		0	$V_{CCA}$	V
	High lovel output output	V <sub>CCA</sub> = 2.3 V		-18	A
I <sub>OH</sub>	High-level output current	V <sub>CCA</sub> = 3 V		-24	mA
	Landard color const	V <sub>CCA</sub> = 2.3 V		18	^
I <sub>OL</sub>	Low-level output current	V <sub>CCA</sub> = 3 V		24	mA
Δt/Δν	Input transition rise or fall rate	•		10	ns/V
_		CALVC16245I	-40	85	٥,
T <sub>A</sub>	Operating free-air temperature	CALVC16245M	-55	125	°C

<sup>(1)</sup> All unused inputs of the device must be held at  $V_{CC}$  or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



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### **Electrical Characteristics**

over recommended operating free-air temperature range for  $V_{CCA}$  = 2.7 V to 3.6 V and  $V_{CCB}$  = 4.5 V to 5.5 V (unless otherwise noted)

D4.D		TEST CONDITIONS		.,	CALV	C164245I	CALVO	164245M	I	LIMIT
PARA	AMETER	TEST CONDITIONS	V <sub>CCA</sub>	V <sub>CCB</sub>	MIN	TYP <sup>(1)</sup> MAX	MIN	TYP <sup>(1)</sup>	MAX	UNIT
		I <sub>OH</sub> = -100 μA	2.7 V to 3.6 V		V <sub>CC</sub> - 0.2		V <sub>CC</sub> - 0.2			
	B to A	I <sub>OH</sub> = -12 mA	2.7 V		2.2		2.2			
		10H = -12 111A	3 V		2.4		2.4			
$V_{OH}$		$I_{OH} = -24 \text{ mA}$	3 V		2		2			V
		I <sub>OL</sub> = 100 μA		4.5 V	4.3		4.3			
	A to B	ΙΟΣ = 100 μΑ		5.5 V	5.3		5.3			
	7 10 5	I <sub>OL</sub> = 24 mA		4.5 V	3.7		3.7			
		10L - 24 111A		5.5 V	4.7		4.7			
	D += A	I <sub>OL</sub> = 100 μA	2.7 V to 3.6 V			0.2			0.2	
	B to A	I <sub>OL</sub> = 12 mA	2.7 V			0.4			0.4	
V <sub>OL</sub>		I <sub>OL</sub> = 24 mA	3 V			0.55			0.55	V
VOL	A to B	I <sub>OL</sub> = 100 μA		4.5 V to 5.5 V		0.2			0.2	
	ALOB	I <sub>OL</sub> = 24 mA		4.5 V to 5.5 V		0.55			0.55	
I <sub>I</sub>	Control inputs	$V_I = V_{CCA}/V_{CCB}$ or GND	3.6 V	5.5 V		±5			±5	μА
I <sub>OZ</sub> <sup>(2)</sup>	A or B port	$V_O = V_{CCA}/V_{CCB}$ or GND	3.6 V	5.5 V		±10			±10	μА
I <sub>CC</sub>		$V_I = V_{CCA}/V_{CCB}$ or GND, $I_O = 0$	5.5 V	5.5 V		40			40	μА
Δl <sub>CC</sub> <sup>(3</sup>	)	One input at $V_{CCA}/V_{CCB} - 0.6 \text{ V}$ , Other inputs at $V_{CCA}/V_{CCB}$ or GND	3 V to 3.6 V	4.5 V to 5.5 V		750			750	μА
C <sub>i</sub>	Control inputs	$V_{I} = V_{CCA}/V_{CCB}$ or GND	3.3 V	5 V		6.5		6.5		pF
C <sub>io</sub>	A or B port	$V_O = V_{CCA}/V_{CCB}$ or GND	3.3 V	3.3 V		8.5		8.5		pF

All typical values are at  $V_{CCA} = 3.3 \text{ V}$  and  $V_{CCB} = 5 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ . For I/O ports, the parameter  $I_{OZ}$  includes the input leakage current. This is the increase in supply current for each input that is at one of the specified TTL voltage levels, rather than at 0 or the associated  $V_{CC}$ .



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## **Electrical Characteristics**

over recommended operating free-air temperature range for  $V_{CCA}$  = 2.3 V to 2.7 V and  $V_{CCB}$  = 3 V to 3.6 V (unless otherwise noted)

DAD	METER	TEST CONDITIONS	v	V	CALVC164245I	CALVC16424	5M	UNIT
PARA	AMETER	TEST CONDITIONS	V <sub>CCA</sub>	V <sub>CCB</sub>	MIN MAX	MIN I	MAX	UNII
		$I_{OH} = -100 \mu A$	2.3 V to 2.7 V	3 V to 3.6 V	V <sub>CCA</sub> - 0.2	V <sub>CCA</sub> - 0.2		
	B to A	$I_{OH} = -8 \text{ mA}$	2.3 V	3 V to 3.6 V	1.7	1.7		
$V_{OH}$		$I_{OH} = -12 \text{ mA}$	2.7 V	3 V to 3.6 V	1.8	1.8		V
	A to B	I <sub>OL</sub> = 100 μA	2.3 V to 2.7 V	3 V to 3.6 V	V <sub>CCB</sub> - 0.2	V <sub>CCB</sub> - 0.2		
		I <sub>OL</sub> = 18 mA	2.3 V to 2.7 V	3 V	2.2	2.2		
	B to A	I <sub>OL</sub> = 100 μA	2.3 V to 2.7 V	3 V to 3.6 V	0.2		0.2	
\/		I <sub>OL</sub> = 12 mA	2.3 V	3 V to 3.6 V	0.6		0.6	V
V <sub>OL</sub>	A to D	I <sub>OL</sub> = 100 μA	2.3 V to 2.7 V	3 V to 3.6 V	0.2		0.2	v
	A to B	I <sub>OL</sub> = 18 mA	2.3 V	3 V	0.55		0.55	
I	Control inputs	$V_I = V_{CCA}/V_{CCB}$ or GND	2.3 V to 2.7 V	3 V to 3.6 V	±5		±5	μΑ
I <sub>OZ</sub> <sup>(1)</sup>	A or B port	$V_O = V_{CCA}/V_{CCB}$ or GND	2.3 V to 2.7 V	3 V to 3.6 V	±10		±10	μΑ
I <sub>CC</sub>		$V_I = V_{CCA}/V_{CCB}$ or GND, $I_O = 0$	2.3 V to 2.7 V	3 V to 3.6 V	20		40	μΑ
Δl <sub>CC</sub> <sup>(2</sup>	)	One input at V <sub>CCA</sub> /V <sub>CCB</sub> – 0.6 V, Other inputs at V <sub>CCA</sub> /V <sub>CCB</sub> or GND	2.3 V to 2.7 V	3 V to 3.6 V	750		750	μΑ

For I/O ports, the parameter  $I_{OZ}$  includes the input leakage current. This is the increase in supply current for each input that is at one of the specified TTL voltage levels, rather than at 0 or the associated  $V_{\text{CC}}. \\$ 



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## **Switching Characteristics**

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1 through Figure 4)

			CALVC16245I					
DADAMETED	FROM	TO (OUTPUT)	V <sub>CCB</sub> = 3.3 V ± 0.3 V	V	$V_{CCB}$ = 5 V $\pm$ 0.5 V			UNIT
PARAMETER	(INPUT)		V <sub>CCA</sub> = 2.5 V ± 0.2 V	V <sub>CCA</sub> =	V <sub>CCA</sub> = 2.7 V		$V_{CCA}$ = 3.3 V $\pm$ 0.3 V	
			MIN MA	MIN	MAX	MIN	MAX	
4	А	В	7.	6	5.9	1	5.8	20
t <sub>pd</sub>	В	A	7.	6	6.7	1.2	5.8	ns
t <sub>en</sub>	ŌĒ	В	11.	5	9.3	1	8.9	ns
t <sub>dis</sub>	ŌĒ	В	10.	5	9.2	2.1	9.5	ns
t <sub>en</sub>	ŌĒ	A	12.	3	10.2	2	9.1	ns
t <sub>dis</sub>	ŌĒ	A	9.	3	9	2.9	8.6	ns

## **Switching Characteristics**

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1 through Figure 4)

PARAMETER	FROM	то	V <sub>CCB</sub> = 3.3 V ± 0.3 V	V <sub>CCB</sub> = 5			
	(INPUT)	(OUTPUT)	V <sub>CCA</sub> = 2.5 V ± 0.2 V	V <sub>CCA</sub> = 2.7 V	$V_{CCA} = 3.3 V$ $\pm 0.3 V$		UNIT
			MIN MAX	MIN MAX	MIN	MAX	
4	Α	В	8.6	6.9	1	6.8	no
t <sub>pd</sub>	В	Α	8.6	7.7	1.2	6.8	ns
t <sub>en</sub>	ŌĒ	В	12.5	10.3	1	9.9	ns
t <sub>dis</sub>	ŌĒ	В	11.5	10.2	2.1	10.5	ns
t <sub>en</sub>	ŌĒ	Α	14.5	11.2	2	10.1	ns
t <sub>dis</sub>	ŌĒ	Α	11.3	11	2.9	10.6	ns

## **Operating Characteristics**

 $T_A = 25^{\circ}C$ 

	PARAMETER		TEST CONDITIONS	$V_{CCB} = 3.3 \text{ V}$ $V_{CCA} = 2.5 \text{ V}$ TYP	$V_{CCB} = 5 V$ $V_{CCA} = 3.3 V$ TYP	UNIT
		Outputs enabled (B)	C <sub>L</sub> = 50 pF, f = 10 MHz	55	56	
_	Power dissipation capacitance	Outputs disabled (B)		27	6	
Cpd	pu , ,	Outputs enabled (A)	C 50 °F \$ 10 MHz	118	56	pF
		Outputs disabled (A)	$C_L = 50 \text{ pF},  f = 10 \text{ MHz}$	58	6	

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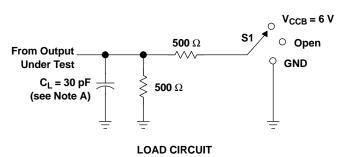
### Power-Up Considerations(1)

TI level-translation devices offer an opportunity for successful mixed-voltage signal design. A proper power-up sequence always should be followed to avoid excessive supply current, bus contention, oscillations, or other anomalies caused by improperly biased device pins. To guard against such power-up problems, take these precautions:

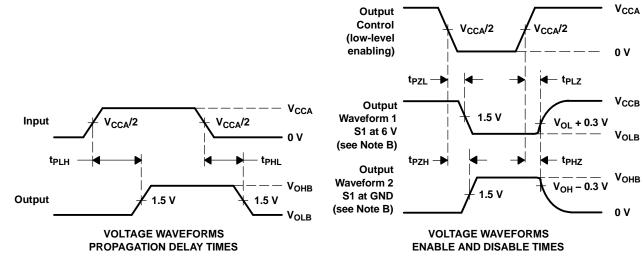
- 1. Connect ground before any supply voltage is applied.
- 2. Power up the control side of the device (V<sub>CCA</sub> for all four of these devices).
- 3. Tie  $\overline{OE}$  to  $V_{CCA}$  with a pullup resistor so that it ramps with  $V_{CCA}$ .
- 4. Depending on the direction of the data path, DIR can be high or low. If DIR high is needed (A data to B bus), ramp it with  $V_{CCA}$ . Otherwise, keep DIR low.
- (1) Refer to the TI application report, Texas Instruments Voltage-Level-Translation Devices, literature number SCEA021.

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## PARAMETER MEASUREMENT INFORMATION $V_{CCA}$ = 2.5 V $\pm$ 0.2 V to $V_{CCB}$ = 3.3 V $\pm$ 0.3 V



TEST	<b>S</b> 1
t <sub>pd</sub>	Open
t <sub>PLZ</sub> /t <sub>PZL</sub>	$V_{CCB} = 6 V$
t <sub>PHZ</sub> /t <sub>PZH</sub>	GND

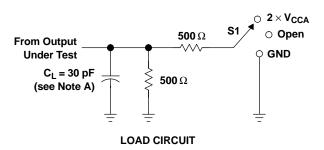


- NOTES: A. C<sub>L</sub> includes probe and jig capacitance.
  - B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
  - C. All input pulses are supplied by generators having the following characteristics: PRR $\leq$ 10 MHz,  $Z_0 = 50 \Omega$ ,  $t_f \leq$ 2 ns.
  - D. The outputs are measured one at a time, with one transition per measurement.
  - E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
  - F. t<sub>PZL</sub> and t<sub>PZH</sub> are the same as t<sub>en</sub>.
  - G.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .

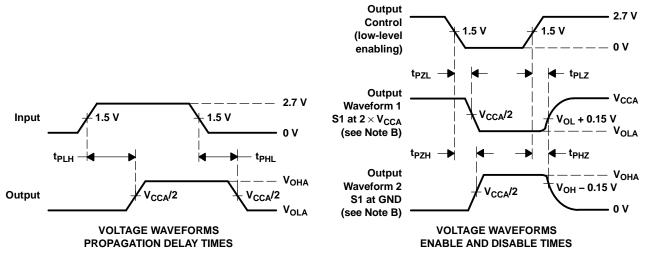
Figure 1. Load Circuit and Voltage Waveforms



## PARAMETER MEASUREMENT INFORMATION $V_{CCB}$ = 3.3 V $\pm$ 0.3 V to $V_{CCA}$ = 2.5 V $\pm$ 0.2 V



TEST	S1
t <sub>pd</sub>	Open
t <sub>PLZ</sub> /t <sub>PZL</sub>	$2 \times V_{CCA}$
t <sub>PHZ</sub> /t <sub>PZH</sub>	GND

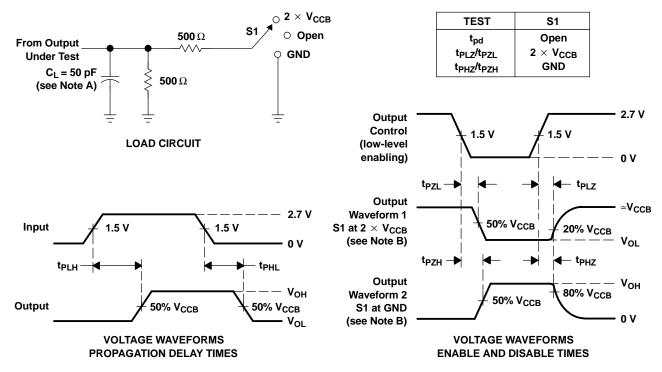


- NOTES: A. C<sub>L</sub> includes probe and jig capacitance.
  - B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
  - C. All input pulses are supplied by generators having the following characteristics: PRR $\le$ 10 MHz,  $Z_0 = 50 \,\Omega$ ,  $t_r \le 2 \,$ ns,  $t_f \le 2 \,$ ns.
  - D. The outputs are measured one at a time, with one transition per measurement.
  - E. t<sub>PLZ</sub> and t<sub>PHZ</sub> are the same as t<sub>dis</sub>.
  - F. t<sub>PZL</sub> and t<sub>PZH</sub> are the same as t<sub>en</sub>.
  - G.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .

Figure 2. Load Circuit and Voltage Waveforms

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## PARAMETER MEASUREMENT INFORMATION $V_{CCA}$ = 3.3 V $\pm$ 0.3 V to $V_{CCB}$ = 5 V $\pm$ 0.5 V



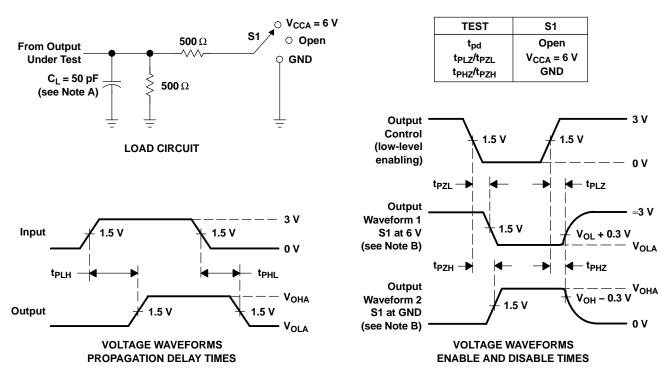
NOTES: A. C<sub>I</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_Q = 50~\Omega$ ,  $t_f \leq$  2.5 ns,  $t_f \leq$  2.5 ns.
- D. The outputs are measured one at a time, with one transition per measurement.
- E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
- F. t<sub>PZL</sub> and t<sub>PZH</sub> are the same as t<sub>en</sub>.
- G. t<sub>PLH</sub> and t<sub>PHL</sub> are the same as t<sub>pd</sub>.

Figure 3. Load Circuit and Voltage Waveforms



## PARAMETER MEASUREMENT INFORMATION $V_{CCB}$ = 5 V $\pm$ 0.5 V to $V_{CCA}$ = 2.7 V and 3.3 V $\pm$ 0.3 V

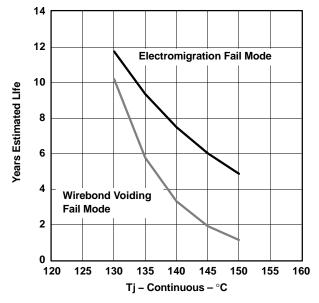


- NOTES: A. C<sub>L</sub> includes probe and jig capacitance.
  - B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
  - C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_{O}$  = 50  $\Omega$ ,  $t_{f} \leq$  2.5 ns.  $t_{f} \leq$  2.5 ns.
  - D. The outputs are measured one at a time, with one transition per measurement.
  - E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
  - F.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .
  - G. t<sub>PLH</sub> and t<sub>PHL</sub> are the same as t<sub>pd</sub>.

Figure 4. Load Circuit and Voltage Waveforms

SCAS774A-JUNE 2004-REVISED SEPTEMBER 2005

# 74ALVC164245MDGG\*EP Estimated Device Life at Elevated Temperatures Electromigration and Wirebond Voiding Fail Modes



A. Silicon operating life design goal is 10 years at 105°C junction temperature.





.com 18-Sep-2008

### **PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
CALVC164245IDGGREP	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CALVC164245IDLREP	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CALVC164245MDGGREP	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
V62/05612-01XE	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
V62/05612-01YE	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
V62/05612-02YE	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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#### OTHER QUALIFIED VERSIONS OF SN74ALVC164245-EP:

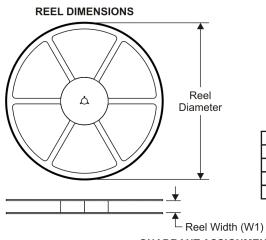
• Catalog: SN74ALVC164245

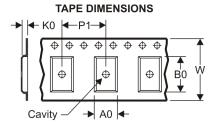
NOTE: Qualified Version Definitions:

Catalog - TI's standard catalog product



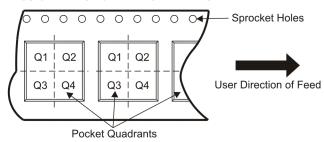
### TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

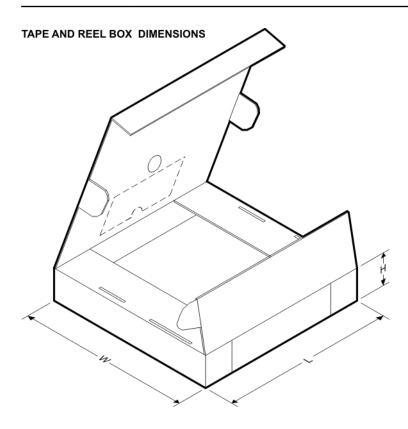
### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CALVC164245IDGGREP	TSSOP	DGG	48	2000	330.0	24.4	8.6	15.8	1.8	12.0	24.0	Q1
CALVC164245IDLREP	SSOP	DL	48	1000	330.0	32.4	11.35	16.2	3.1	16.0	32.0	Q1
CALVC164245MDGGREP	TSSOP	DGG	48	2000	330.0	24.4	8.6	15.8	1.8	12.0	24.0	Q1





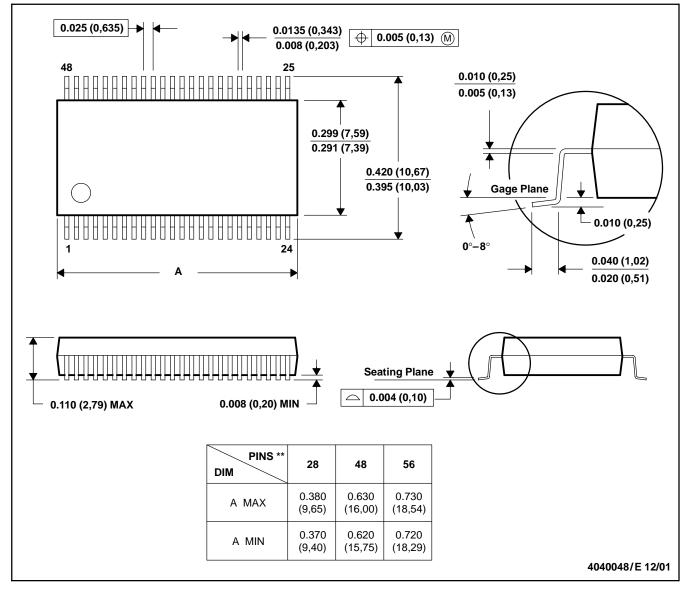
\*All dimensions are nominal

7 til dillionolorio are nominal							
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CALVC164245IDGGREP	TSSOP	DGG	48	2000	346.0	346.0	41.0
CALVC164245IDLREP	SSOP	DL	48	1000	346.0	346.0	49.0
CALVC164245MDGGREP	TSSOP	DGG	48	2000	346.0	346.0	41.0

### DL (R-PDSO-G\*\*)

### **48 PINS SHOWN**

### PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MO-118

## DGG (R-PDSO-G\*\*)

## PLASTIC SMALL-OUTLINE PACKAGE

### **48 PINS SHOWN**



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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